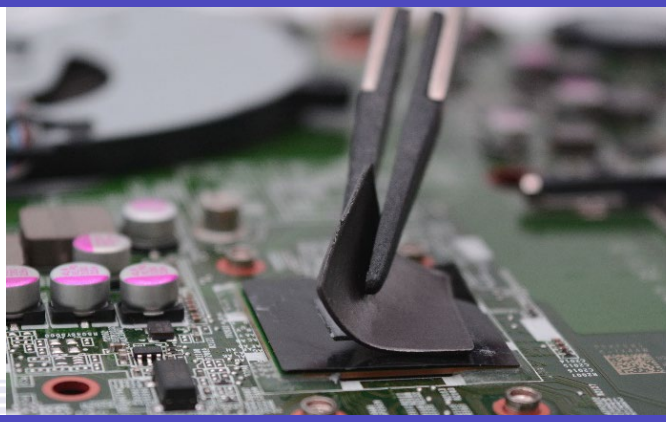
Thermexit™

Thermexit-HP-40
P/N: 08-0059-0.1

KEY FEATURES

PRODUCT FEATURES:

- Non-silicone, non-reactive, non-curing system with no resin-filler separation
- High thermal stability, with continuous operation up to 150°C
- High thermal conductivity (40W/mK)
- Easy pick and place application (naturally sticky) without residue/mess
- Highly compressible to minimize contact resistance without high force and component stress



TECHNICAL SPECIFICATIONS

Test	Description	Min	Max
Thermal Conductivity *	ASTM D5470	40 W/mK	
Thermal Impedance vs Pressure **	ASTM D5470	0.56°C-cm²/W (0.087°C-inch²/W) @10psi 0.37°C-cm²/W (0.057°C-inch²/W) @30psi	
Continuous Use Temperature	Thermexit In-House Method	-40°C	150°C
Storage Temperature/Shelf Life	Thermexit In-House Method	10-40°C for 12 months	
Total Mass Loss/TGA *	Thermal stability (TGA)	<0.2% @150°C	
Hardness *	ASTM D2240	70 Shore 00	80 Shore 00
Outgassing CVCM (Collectible Volatile Condensable Materials)	ASTM E595	0.10 Wt. %	
Outgassing TML (Total Mass Loss)	ASTM E595	0.47 Wt. %	
Compression-Deflection **	ASTM D5470/ASTM C165	50% at 45psi	
Compression Set *	ASTM D395 Method B	64% after 22hrs at RT	
Length	Major axis of the pad footprint, +/-10%	5mm	50mm
Width	Minor axis of the pad footprint, +/-10%	5mm	50mm
Thickness	Thickness of the pad, +/-10%	0.5mm	5mm
Density (Specific Gravity) *	ASTM D0792	1.73 g/mL	
Standard Color	Thermexit In-House Method	Black	
Flammability	UL94 Vertical	V1	

Standard sizes are 20mm x 20mm or 50mm x 50mm. Custom sizes available upon request.
*Preliminary Data, **1.5mm thickness: additional data available

RoHS compliant

REACH COMPLIANCE

Thermexit™

TYPICAL APPLICATIONS

MARKET APPLICATIONS

- Consumer electronics
- Power supplies
- Automotive electronics
- LED, LCD and optical display
- Motor controls
- High power density semiconductors
- Batteries or energy storage devices